

ABSTRACT

A tiedown structure including a semiconductor substrate having a chip formed thereon, a kerf region, and a conductive connector forming a connection between the chip and the kerf region. Alternatively, the conductive connector connects an edge seal surrounding the chip and a chip portion. A method for forming a semiconductor structure includes forming a device on a chip, defining a kerf proximate the chip, and forming a conductive connector that connects the device and the kerf. An end of the conductive connector is removed by sawing, etching, or focused ion beam milling. A method for forming a semiconductor structure includes forming a chip on a semiconductor substrate, the chip including a device; forming an edge seal along a perimeter of the chip; and forming a conductive connector that connects the edge seal and the device. A conductive connector portion is removed by etching or focused ion beam milling.

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